

FE Electronics: TDC, Clocking & Control

John Jones

High Energy Physics Group
Princeton University

20th November 2008 / SLHC Workshop, FNAL

Outline

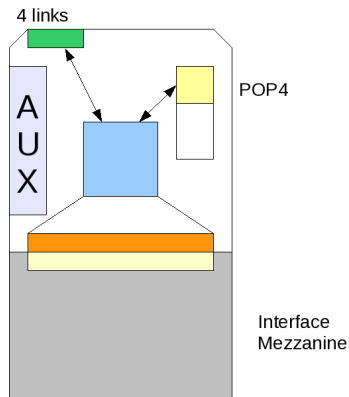
- ▶ Requirements for TDC, clocking, etc...
- ▶ μ DAQ card
- ▶ 4-phase TDC + clocks in a Xilinx Virtex-5
- ▶ SEU mitigation & scrubbing

Requirements

- ▶ Phased clock per QIE
- ▶ TDC per channel
- ▶ Configuration of QIEs
- ▶ (Unforeseen) additional functionality

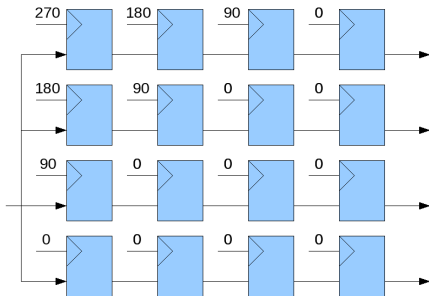
Prototyping platform for QIE/MPPC readout

- ▶ Designed to inter-operate with μ TCA standard for testing
- ▶ Will also operate on a bench (or in a test-beam)
- ▶ Small Xilinx Virtex-5 for development
- ▶ Radiation tolerance taken into account (e.g. Enpirion power supplies)
- ▶ Simple configuration scrubbing via SelectMAP
- ▶ Many external I/O to connect to QIEs



TDC

- ▶ Folds input signal into 4 phase-shifted registers
- ▶ A variant of this was implemented in T2K with a Xilinx Spartan-3 (2.5ns resolution)
- ▶ In a Virtex-5, this increases to 0.5ns resolution (500MHz clock, 4 phases)
- ▶ Still need discriminator input (TBD)



QIE Clocking

- ▶ Use serialised output at multiple of LHC clock
- ▶ With DDR, resolution of 0.5ns-2ns should be achievable (needs further study)
- ▶ Minimal resource usage

- ▶ V5s support readback CRC and new scrubbing features
- ▶ Firmware configuration is now Hamming coded
- ▶ Single bit & double bit detection now possible
- ▶ Software implementation of firmware checker implemented
- ▶ Other parts of design must be made triple redundant

- ▶ Prototype / test in Xilinx Virtex-5
- ▶ Finalise algorithms / readout
- ▶ Implement in antifuse or ASIC for final design